



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C120JB81PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 12pF, 50V, ±5%, C0G, 0603

• AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u>	<u>10</u>	<u>C</u>	<u>120</u>	<u>J</u>	<u>B</u>	<u>8</u>	<u>1</u>	<u>P</u>	<u>N</u>	<u>C</u>
①	2	3	4	⑤	6	7	8	9	10	11)

1	Series	Samsung Multi-layer Ceramic	Capaci	tor				
2	Size	0603 (inch code)	L:	1.6	± 0.1 mm	W:	0.8 ± 0.1	mm
3	Dielectric	C0G		8	Inner electrode	N	i	
4	Capacitance	12 pF			Termination	С	u	
(5)	Capacitance	±5 %			Plating	S	n 100%	(Pb Free)
	tolerance			9	Product	А	utomotive	
6	Rated Voltage	50 V		10	Grade code	S	tandard	
7	Thickness	0.8 ± 0.1 mm		11)	Packaging	С	ardboard Typ	e, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150°C
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±2.5% or ±0.25pF whichever is larger	
	Q: 640 min	
	IR : More than 10,000⋒ or 500⋒∡x <i>µ</i> F	
	Whichever is Smaller	
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles
	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :
	Q: 640 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)
	IR : More than 10,000MΩ or 500MΩ×μF	-> 125+3/-0 °C (15±3min) -> Room Temp(1min.)
	Whichever is Smaller	
Destructive Physical	No Defects or abnormalities	Per EIA 469
Analysis		
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle
	Capacitance Change :	Heat (25~65℃) and humidity (80~98%), Unpowered
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion
	Q: 305 min	
	IR : More than 10,000MΩ or 500MΩ×μF	
	Whichever is Smaller	
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 ℃/85%RH, Rated Voltate and 1.3~1.5V,
	Capacitance Change :	Add 100kohm resistor
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion
	Q: 140 min	The charge/discharge current is less than 50mA.
	IR : More than 500MΩ or 25MΩ×μF	
	Whichever is Smaller	
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125℃, 200% Rated Voltage,
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.
	Q: 305 min	
	IR : More than 10,000№ or 500№× <i>μ</i> F	
	Whichever is Smaller	

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope ('10)					
	appearance						
Physical Dimensions	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)					
	within ±2.5% or ±0.25pF whichever is larger	Peakvalue Duration Wave Velocity					
	Q, IR : initial spec.	1,500G 0.5ms Half sine 4.7m/sec.					
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,					
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side					
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted					
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000 Hz.					
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5°C, 10±1sec.					
Solder Heat	Capacitance Change :						
	within ±2.5% or ±0.25pF whichever is larger						
	Q, IR : initial spec.						
Thermal Shock	Appearance : No abnormal exterior appearance	-55℃/+125℃.					
	Capacitance Change :	Note: Number of cycles required-300,					
	within ±2.5% or ±0.25pF whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air					
	Q, IR : initial spec.						
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002					
	Capacitance Change :						
	within ±2.5% or ±0.25pF whichever is larger						
	Q, IR : initial spec.						
Solderability	95% of the terminations is to be soldered	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C					
Electrical Control	O NEW YEAR	solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	The Capacitance /Q should be measured at 25 ℃,					
Characterization	Q: 640 max.	1Mb±10%, 0.5~5Vrms					
	IR(25 °C): More than 100,000 MΩ or 1,000 MΩ × μF	I.R. should be measured with a DC voltage not exceeding					
	IR(125℃): More than10,000MΩ or 100MΩ×μF	Rated Voltage @25°C, @125°C for 60~120 sec.					
	Whichever is Smaller	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Doord Flow	Dielectric Strength Appearance : No abnormal exterior appearance	Danding to the limit /2 \ for F accords					
Board Flex	1	Bending to the limit (3mm) for 5 seconds					
	Capacitance Change : within ±5.0% or ±0.5pF whichever is larger						
Terminal	Appearance : No abnormal exterior appearance	10N, for 60±1 sec.					
Strength(SMD)	Capacitance Change :	TOIN, TOI OUET Sec.					
Strength(SMD)	within ±2.5% or ±0.25pF whichever is larger						
Beam Load	Destruction value should not be exceed	Beam speed					
Dodin Load	Chip Length < 2.5mm	0.5±0.05mm/sec					
	a) Chip Thickness > 0.5mm : 20N	515_515Gmm/ 666					
	a) Crip Trickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N						
Temperature	COG						
Characterisitcs		ne within +30PPM/°C)					
- iai aoto i oitos	(From -55℃ to 125℃, Capacitance change shoud be within ±30PPM/℃)						

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.